

ABSTRACT

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Printed tape is used to form a leads on chip (LOC) ball grid array (BGA) semiconductor device. Leads for a plurality of devices may be applied simultaneously. Bond wires, glob top encapsulant, and the ball grid arrays for the devices may be formed in single process steps. A low temperature curing adhesive material may be used to reduce the effects of differential thermal expansion between the tape and surface of the wafer. In another embodiment of the invention, anisotropically conductive adhesive material is used to connect bond pads on a wafer to leads printed on a tape.